

	Hit s	Search Text	DBs
27	1	((substrate or wafer) same (radiation\$4sensitive or photoresist or resist or photo\$4imageable)) and ((expos\$4 or irradiat\$4 or illuminat\$4) same ((immers\$5 near9 (lithograph\$4 or photolithograph\$4 or projection)) or (project\$3 near4 (apparatus or system or align\$4) near5 (immers\$4 or liquid) near6 gap))) and ((substrate or wafer) same (rotation or rotational or rotating) same (dry\$4 or heat\$4 or bak\$3) same (liquid or fluid or immers\$4)) and ((integrat\$3 near5 circuit\$3) or (circuit\$4 near4 device)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
28	7	((substrate or wafer) same (radiation\$4sensitive or photoresist or resist or photo\$4imageable)) and ((expos\$4 or irradiat\$4 or illuminat\$4) same ((immers\$5 near9 (lithograph\$4 or photolithograph\$4 or projection)) or (project\$3 near4 (apparatus or system or align\$4) near5 (immers\$4 or liquid) near6 gap))) and ((substrate or wafer) same (appl\$6 or coat\$4 or deposit\$4 or form\$3) same (fluid or alcohol) same dry\$4) and ((integrat\$3 near5 circuit\$3) or (circuit\$4 near4 device)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
29	7	((substrate or wafer) same (radiation\$4sensitive or photoresist or resist or photo\$4imageable)) and ((expos\$4 or irradiat\$4 or illuminat\$4) same (immers\$5 near9 (lithograph\$4 or photolithograph\$4 or projection))) and ((substrate or wafer) same (appl\$6 or coat\$4 or deposit\$4 or form\$3) same (fluid or alcohol) same dry\$4) and ((integrat\$3 near5 circuit\$3) or (circuit\$4 near4 device)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
30	1	((substrate or wafer) same (radiation\$4sensitive or photoresist or resist or photo\$4imageable)) and ((expos\$4 or irradiat\$4 or illuminat\$4) same (immers\$5 near9 (lithograph\$4 or photolithograph\$4 or projection))) and ((substrate or wafer) same (dry\$4 or heat\$4 or bak\$3) same (non\$4uniform\$4 or unifor\$4) same (CD or (critical near5 dimension))) and ((integrat\$3 near5 circuit\$3) or (circuit\$4 near4 device)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
31	2	((substrate or wafer) same (radiation\$4sensitive or photoresist or resist or photo\$4imageable)) and ((expos\$4 or irradiat\$4 or illuminat\$4) same (immers\$5 near9 (lithograph\$4 or photolithograph\$4 or projection))) and ((substrate or wafer) same (dry\$4 or heat\$4 or bak\$3) same (non\$4uniform\$4 or unifor\$4 or resolut\$4) same (CD or (critical near5 dimension)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
32	2	((substrate or wafer) same (radiation\$4sensitive or photoresist or resist or photo\$4imageable)) and ((expos\$4 or irradiat\$4 or illuminat\$4) same (immers\$5 near9 (lithograph\$4 or photolithograph\$4 or projection or lens\$3))) and ((substrate or wafer) same (dry\$4 or heat\$4 or bak\$3) same (non\$4uniform\$4 or unifor\$4 or resolut\$4) same (CD or (critical near5 dimension)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
33	12	((substrate or wafer) same (radiation\$4sensitive or photoresist or resist or photo\$4imageable)) and ((expos\$4 or irradiat\$4 or illuminat\$4) same (immers\$5 near9 (lithograph\$4 or photolithograph\$4 or projection or lens\$3))) and ((substrate or wafer) same (dry\$4 or heat\$4 or bak\$3) same (coupl\$3 or attach\$4 same conveyor or in\$3line or insitu or track) same (system or dry\$4 or spray))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB